

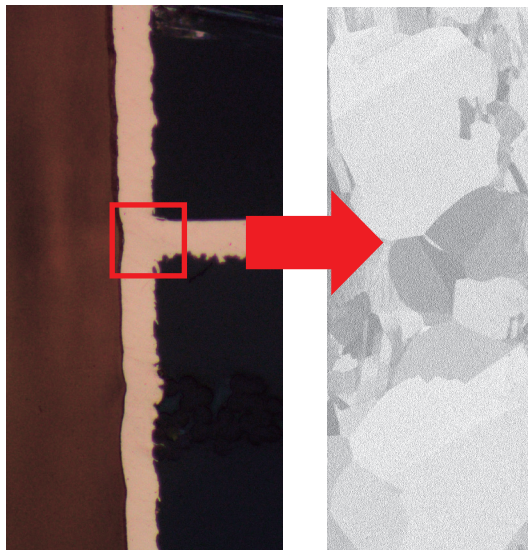
Electroless copper plating process with high covering performance

OPC SUBLET PROCESS Subtractive Process

- High covering performance on glass cloth and filler in hole
- Improve thickness uniformity in hole, realize high throwing power
- Control the electroless copper deposition, achieve no interface with plated Cu and inner copper layer

Strongly improve connection reliability with inner copper layer

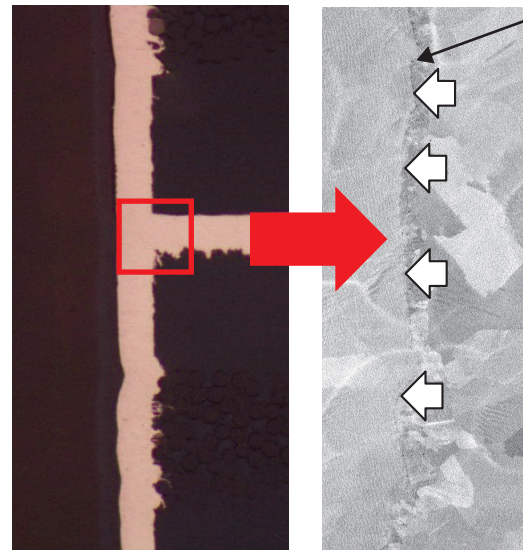
OPC SUBLET PROCESS



Cu electroplating Inner copper layer

No interface

Conventional

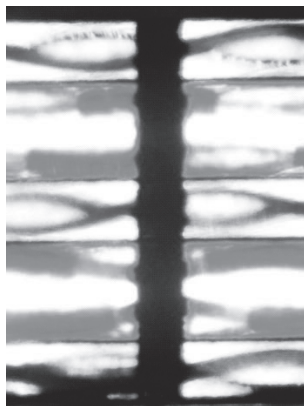


Cu electroplating Inner copper layer

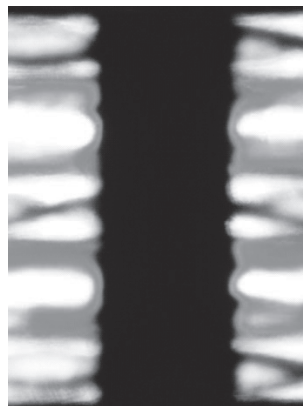
Interface

High deposition performance into holes

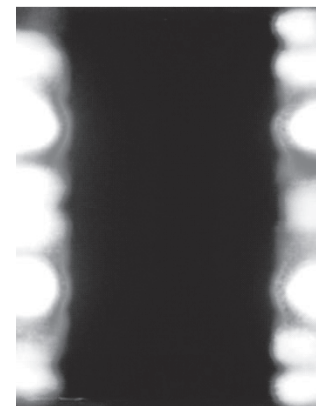
Back light test



Hole diameter 0.2 mm



Hole diameter 0.6 mm



Hole diameter 1.0 mm

Board thickness: 1.6 mm